# KYOCERA KE-300AH

Epoxy; Epoxide

KYOCERA Chemical Corporation

## Message:

High Reliable and Easy-to-Use Molding Compounds for Various Type of Packages
Strong Points
Provide Various Molding Compounds with High Reliability to Cover Many Applications such as LSI, Transistors and Diodes.
Good Curability and Applicable to Various Molding Machines (Both Automated and Conventional)
Low Stress of Large chips and Applicable to Encapsulation.
Application
Smaller SOP, Smaller QFP, DIP, SIP/ZIP, TO-PKG, DPAK, SOT, Unbalanced PKG, Module

| General Information | | |
|---|---|---|
| Uses | Electrical/Electronic Applications | |
| **Physical** | **Nominal Value** | **Unit** |
| Specific Gravity | 1.90 | g/cm³ |
| Spiral Flow | 90.0 | cm |
| **Mechanical** | **Nominal Value** | **Unit** |
| Flexural Modulus | 13500 | MPa |
| Flexural Strength | 150 | MPa |
| **Thermal** | **Nominal Value** | **Unit** |
| Glass Transition Temperature | 155 | °C |
| CLTE - Flow | | |
| -- [1] | 1.5E-5 | cm/cm/°C |
| -- [2] | 5.5E-5 | cm/cm/°C |
| **Uncured Properties** | **Nominal Value** | **Unit** |
| Gel Time | 0.37 | min |
| **NOTE** | | |
| 1. | Alpha 1 | |
| 2. | Alpha 2 | |

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